

Low Resistance Resettable Fuse PTC SMD0603 Series

Features



RoHS Compliant & Halogen Free

faster tripping, 0603 Dimension, Surface mountable, Solid state

Operation Current: 0.35A~3.0A

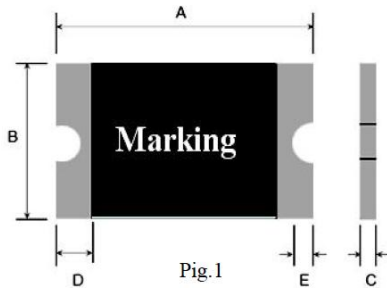
Maximum Voltage: 6V

Operating Temperature: -40°C to +85°C

Agency recognition: RoHS



Dimensions(1608mm / 0603 mils) Unit: mm



| Part number | Marking | A | | B | | C | | D | E | UL | TUV | Delivery Time | |
|------------------|---------|------|------|------|------|-----|-----|------|-----|----|-----|---------------|---------|
| | | Min | max | Min | Max | Min | Max | Min | Min | | | in stock | Produce |
| JK-SMD-0603-035L | A | 1.45 | 1.85 | 0.65 | 1.05 | 0.3 | 0.7 | 0.15 | 0.1 | - | - | 3days | 18days |
| JK-SMD-0603-050L | A | 1.45 | 1.85 | 0.65 | 1.05 | 0.3 | 0.7 | 0.15 | 0.1 | - | - | 3days | 18days |
| JK-SMD-0603-075L | A | 1.45 | 1.85 | 0.65 | 1.05 | 0.3 | 0.7 | 0.15 | 0.1 | - | - | 3days | 18days |
| JK-SMD-0603-100L | B | 1.45 | 1.85 | 0.65 | 1.05 | 0.4 | 1.0 | 0.15 | 0.1 | - | - | 3days | 18days |
| JK-SMD-0603-125L | B | 1.45 | 1.85 | 0.65 | 1.05 | 0.4 | 1.0 | 0.15 | 0.1 | - | - | 3days | 18days |
| JK-SMD-0603-150L | C | 1.45 | 1.85 | 0.65 | 1.05 | 0.5 | 1.2 | 0.15 | 0.1 | - | - | 3days | 18days |
| JK-SMD-0603-175L | C | 1.45 | 1.85 | 0.65 | 1.05 | 0.5 | 1.2 | 0.15 | 0.1 | - | - | 3days | 18days |
| JK-SMD-0603-200L | C | 1.45 | 1.85 | 0.65 | 1.05 | 0.7 | 1.4 | 0.15 | 0.1 | - | - | 3days | 18days |
| JK-SMD-0603-260L | E | 1.45 | 1.85 | 0.65 | 1.05 | 0.7 | 1.4 | 0.15 | 0.1 | - | - | 3days | 18days |
| JK-SMD-0603-300L | E | 1.45 | 1.85 | 0.65 | 1.05 | 0.7 | 1.4 | 0.15 | 0.1 | - | - | 3days | 18days |

Electrical characteristics(25°C)



| Part Number | I _{Hold} | I _{Trip} | V _{max} | I _{max} | P _d Max | Maximum Time to Trip | | Resistance (Ω) | | Certification | | Delivery Time | |
|------------------|-------------------|-------------------|------------------|------------------|--------------------|----------------------|----------|-------------------|-------------------|---------------|-----|---------------|---------|
| | A | A | DC | A | w | Current (A) | Time (S) | R _{imin} | R _{1max} | UL | TUV | in stock | Produce |
| JK-SMD-0603-035L | 0.35 | 0.70 | 6.0V | 50 | 0.50 | 8.0 | 0.1 | 0.15 | 1.0 | - | - | 3days | 18days |
| JK-SMD-0603-050L | 0.5 | 1.0 | 6.0V | 50 | 0.50 | 8.0 | 0.6 | 0.07 | 0.4 | - | - | 3days | 18days |
| JK-SMD-0603-075L | 0.75 | 1.5 | 6.0V | 50 | 0.50 | 8.0 | 1.0 | 0.055 | 0.25 | - | - | 3days | 18days |
| JK-SMD-0603-100L | 1.0 | 2.0 | 6.0V | 50 | 0.50 | 8.0 | 2.0 | 0.045 | 0.12 | - | - | 3days | 18days |
| JK-SMD-0603-125L | 1.25 | 2.5 | 6.0V | 50 | 0.50 | 8.0 | 3.0 | 0.035 | 0.10 | - | - | 3days | 18days |
| JK-SMD-0603-150L | 1.5 | 3.0 | 6.0V | 50 | 0.50 | 8.0 | 4.0 | 0.025 | 0.08 | - | - | 3days | 18days |
| JK-SMD-0603-175L | 1.75 | 3.5 | 6.0V | 50 | 0.50 | 8.0 | 5.0 | 0.015 | 0.07 | - | - | 3days | 18days |
| JK-SMD-0603-200L | 2.0 | 4.0 | 6.0V | 50 | 0.50 | 8.0 | 5.0 | 0.012 | 0.06 | - | - | 3days | 18days |
| JK-SMD-0603-260L | 2.6 | 5.2 | 6.0V | 50 | 0.50 | 8.0 | 5.0 | 0.008 | 0.05 | - | - | 3days | 18days |
| JK-SMD-0603-300L | 3.0 | 6.0 | 6.0V | 50 | 0.50 | 8.0 | 5.0 | 0.008 | 0.04 | - | - | 3days | 18days |

I_{hold} = Hold Current. Maximum current device will not trip in 25°C still air.

I_{trip} = Trip Current. Minimum current at which the device will always trip in 25°C still air.

V_{max} = Maximum operating voltage device can withstand without damage at rated current (I_{max}).

I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max}).

P_d = Maximum power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.

R_{imin/max} = Minimum/Maximum device resistance prior to tripping at 25°C.

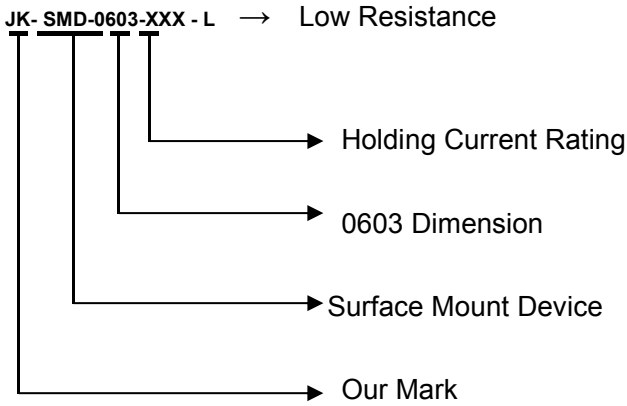
R_{1max} = Maximum device resistance is measured one hour post reflow.

Thermal Derating Chart-IH(A)

Maximum ambient operating temperatures °C

| Part Number | -40°C | -20°C | 0°C | 25°C | 40°C | 50°C | 60°C | 70°C | 85°C |
|------------------|-------|-------|------|-------|------|------|------|------|------|
| JK-SMD-0603-035L | 0.46 | 0.40 | 0.37 | 0.35A | 0.29 | 0.25 | 0.24 | 0.20 | 0.14 |
| JK-SMD-0603-050L | 0.66 | 0.57 | 0.53 | 0.50A | 0.41 | 0.36 | 0.34 | 0.28 | 0.21 |
| JK-SMD-0603-075L | 0.99 | 0.85 | 0.79 | 0.75A | 0.61 | 0.44 | 0.30 | 0.17 | 0.07 |
| JK-SMD-0603-100L | 1.32 | 1.14 | 1.05 | 1.00A | 0.82 | 0.73 | 0.69 | 0.56 | 0.41 |
| JK-SMD-0603-125L | 1.96 | 1.49 | 1.31 | 1.25A | 1.02 | 0.91 | 0.86 | 0.70 | 0.51 |
| JK-SMD-0603-150L | 2.35 | 1.79 | 1.58 | 1.50A | 1.22 | 1.09 | 1.03 | 0.84 | 0.62 |
| JK-SMD-0603-175L | 2.30 | 1.99 | 1.84 | 1.75A | 1.43 | 1.27 | 1.20 | 0.98 | 0.72 |
| JK-SMD-0603-200L | 2.63 | 2.27 | 2.10 | 2.00A | 1.63 | 1.45 | 1.37 | 1.12 | 0.82 |
| JK-SMD-0603-260L | 3.42 | 2.95 | 2.73 | 2.60A | 2.12 | 1.89 | 1.78 | 1.46 | 1.07 |
| JK-SMD-0603-300L | 3.95 | 3.41 | 3.15 | 3.00A | 2.45 | 2.18 | 2.06 | 1.68 | 1.23 |

Part number System



Test Procedures and Requirements

| Test Item | Test Conditions | Accept/Reject Criteria |
|--------------------|-------------------------------------|--------------------------------|
| Initial Resistance | In still air @ 25°C | $R_{min} \leq R \leq R_{1max}$ |
| Time to Trip | Specified current, V_{max} , 25°C | $T \leq$ maximum Time to Trip |
| Hold Current | 30min, at I_H | No trip |
| Trip Cycle Life | V_{max} , I_{max} , 100cycles | No arcing or burning |
| Trip Endurance | V_{max} , 1hours | No arcing or burning |

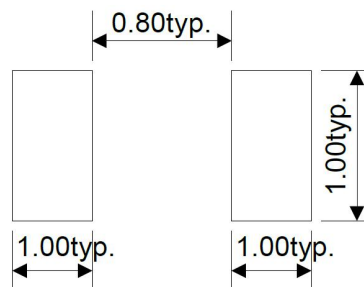
Physical Characteristics

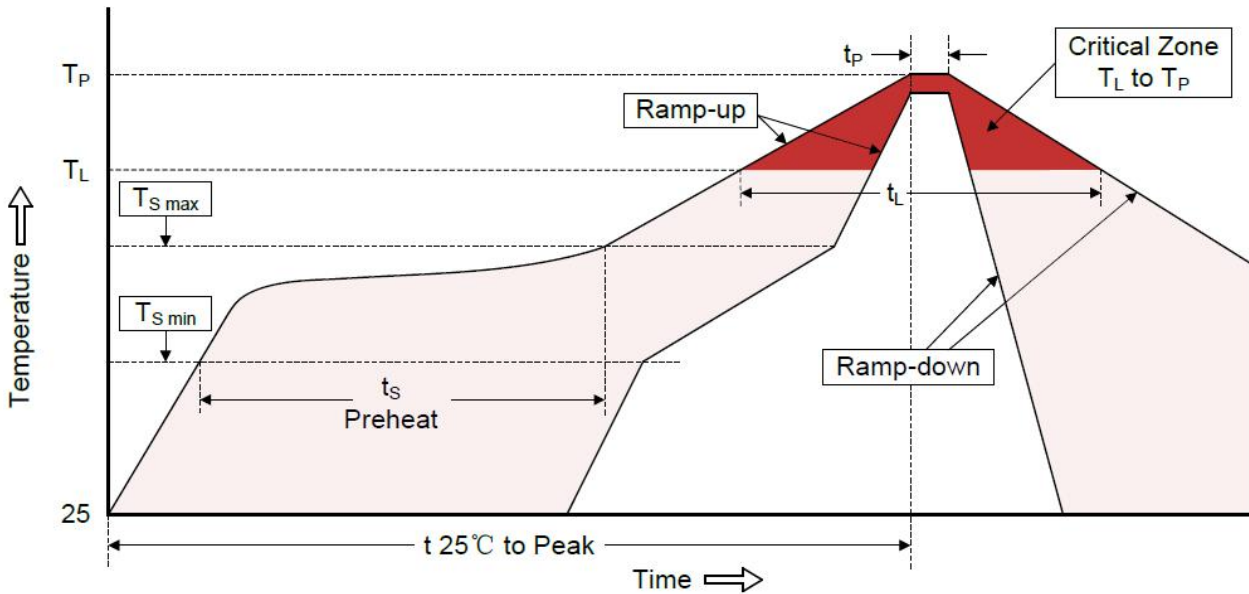
| | |
|----------------------|--|
| Terminal materials : | Tin-Plated Nickle-copper |
| Soldering zone | Meets EIA specification RS 186-9E and ANSI/J-STD-002 Category 3. |
| Moisture Sensitivity | Level 2a, per IPC/JEDEC J-STD 020C |

Environmental Specifications

| Test | Conditions | Resistance change |
|--------------------|--|--------------------------------|
| Passive aging | +85°C, 1000hours | ±10% |
| Humidity aging | +85°C/85%R.H.1000hours | ±5% |
| Thermal shock | MIL-STD-202,Method 107G, +85°C/-40°C,20times | -30% typical resistance change |
| Solvent Resistance | MIL-STD-202,Method 215 | No change |
| Vibration | ML-STD-883C,Test Condition A | No change |

Recommended Pad layout(mm)





| Profile Feature | Pb-Free Assembly |
|---|------------------|
| Average ramp-up rate (TS max to TP) | 3°C/second max. |
| Preheat | |
| -Temperature Min (TS min) | 150°C |
| -Temperature Max (TS max) | 200°C |
| -Time (min to max) (TS min to TS max) | 60-180 seconds |
| Time maintained above: | |
| -Temperature (TL) | 217°C |
| -Time (tL) | 60-150 seconds |
| Peak Temperature (TP) | 260°C |
| Time within 5°C of actual Peak Temperature (tP) | 20-40 seconds |
| Ramp-down Rate | 3°C/second max. |
| Time 25°C to Peak Temperature | 8 minutes max. |
| Storage Condition | 0°C~35°C, ≤70%RH |

- Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead-free.
- Devices are not designed to be wave soldered to the bottom side of the board.
- Recommended maximum paste thickness is 0.25mm (0.010inch).
- Devices can be cleaned using standard industry methods and solvents.

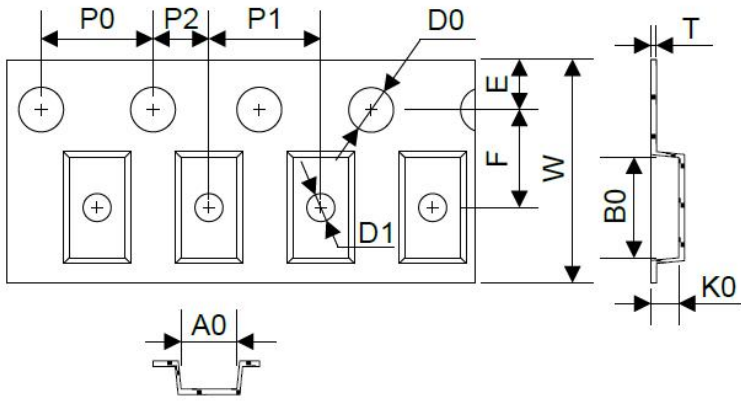
Note 1: All temperature refer to topside of the package, measured on the package body surface.

Note 2: If reflow temperature exceed the recommended profile, devices may not meet the performance requirements.

Tape Specification and Reel Dimensions

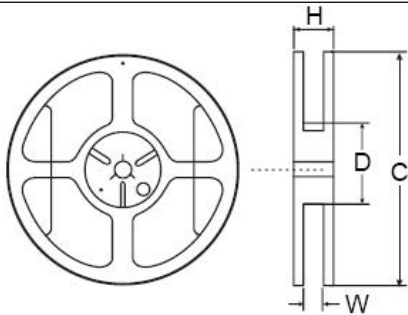


Tape



| Symbol | Dimensions(mm) |
|-------------|----------------|
| W | 8.00±0.30 |
| F | 3.50±0.05 |
| E | 1.75±0.10 |
| D0 | 1.55±0.05 |
| D1 | 0.50±0.10 |
| P0 | 4.00±0.10 |
| P1 | 4.00±0.10 |
| P2 | 2.00±0.05 |
| A0 | 1.10±0.10 |
| B0 | 1.92±0.10 |
| T | 0.20±0.10 |
| K0 | 0.75/0.95±0.10 |
| Leader min | 390 |
| Trailer min | 160 |
| C | Φ178±1.0 |
| D | Φ60.2±0.5 |
| H | 11.0±0.5 |
| W | 9.0±1.5 |

Reel



Packaging Quantity

| Part Number | Quantity | Part Number | Quantity |
|------------------|----------|------------------|----------|
| JK-SMD-0603-035L | 5000pcs | JK-SMD-0603-150L | 4000pcs |
| JK-SMD-0603-050L | 5000pcs | JK-SMD-0603-175L | 4000pcs |
| JK-SMD-0603-075L | 5000pcs | JK-SMD-0603-200L | 4000pcs |
| JK-SMD-0603-100L | 5000pcs | JK-SMD-0603-260L | 4000pcs |
| JK-SMD-0603-125L | 5000pcs | JK-SMD-0603-300L | 4000pcs |

Storage

The maximum ambient temperature shall not exceed 40°C. Storage temperatures higher than 40°C could result in the deformation of packaging materials. The maximum relative humidity recommended for storage is 70%. High humidity with high temperature can accelerate the oxidation of the solder plating on the termination and reduce the solderability of the components. Sealed plastic bags with desiccant shall be used to reduce the oxidation of the termination and shall only be opened prior to use. The products shall not be stored in areas where harmful gases containing sulfur or chlorine are present.

Warning

- Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
- Use PPTC with a large inductance in circuit will generate a circuit voltage ($L di/dt$) above the rated voltage of the PPTC.
- Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.
- Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices. PPTC SMD can be cleaned by standard methods.
- Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layouts or reflow profile could negatively impact solderability performance of our devices.

Notes

The specification is intended to present application, product and technical data to assist the user in selecting PPTC circuit production devices. However, users should independently evaluate and test the suitability of each product. HUAAN makes no warranties as to the accuracy or completeness of the information and disclaims any liability resulting from its use. HUAAN's only obligations are those in the HUAAN Standard Terms and Conditions of Sale and in no case will HUAAN be liable for any incidental, indirect, or consequential damages arising from the sale, resale, or misuse of its products. HUAAN reserves the right to change or update, without notice, any information contained in this specification.